
PRODUCT CHANGE NOTICE

**Alternate Manufacturing Sites
for Intersil ZL1505*,
ZL2004*, and ZL2014*
Products**

**Refer to:
PCN10118**

Date: November 12, 2010

November 12, 2010

To: Our Valued Intersil Customer

Subject: **Alternate Manufacturing Sites for Intersil ZL1505*, ZL2004*, and ZL2014*Products** – *Jazz Semiconductor Newport Beach, CA and STATS ChipPAC Malaysia*

This notice is to inform you that Intersil is qualifying the Jazz Semiconductor Newport Beach, CA and STATS ChipPAC Malaysia (SCM) facilities as alternate sites for performing wafer fabrication and package assembly of the listed ZL1505*, ZL2004*, and ZL2014*products. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. The product and site-specific qualification activities are in progress and scheduled to complete in December 2010.

The Jazz facility is ISO 9001:2008 and ISO/TS 16949:2002 certified and qualified as a supplier to Intersil for wafer fabrication of BCD35 (Bipolar CMOS DMOS) technology products. The STATS ChipPAC Malaysia (SCM) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and qualified as a supplier to Intersil for assembly and testing of DFN/QFN packaged products.

There will be no change in the package outline drawing (POD) except for the maximum package height. The maximum package height will change from 0.90mm to 1.00mm with nominal values of 0.85mm and 0.90mm respectively. The 1.00mm maximum aligns with JEDEC POD MO-220 variation V. There will be no change in the moisture sensitivity level (MSL). The qualified material sets and plating combinations are as follows:

Part Number	Package	Material	Current - ATP	Proposed - SCM
ZL1505	3x3 DFN 10p	Mold Compound Die Attach Lead Finish	CEL 9220 AMK06 Ni/Pd/Au	Sumitomo EME-G770 Ablestik A8290 Matte Sn Finish
ZL2004, ZL2014	5X5 QFN 32p	Mold Compound Die Attach Lead Finish	CEL 9220 AMK06 Ni/Pd/Au	Sumitomo EME-G770 Ablestik A8290 Matte Sn Finish

The wafer fabrication and assembly qualification plans are designed using JEDEC and other applicable industry standards. A summary of the qualification plan and status of completion is included for reference. The qualification results will be available for review upon completion by request.

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at SCM may also be identified by the assembly site code (country of assembly) when marked on the devices. The assembly site code for the SCM facility is "H".

Intersil has created new part numbers (plating designator changed from “N” to F”) to identify product fabricated at Jazz and assembled at SCM. This letter is to request that customers begin using the appropriate new part number(s) for ordering product incorporating the changes outlined in this notification beginning ninety days from the date of this notification or earlier. Upon expiration of the ninety day period, Intersil intends to make the new part number the primary offering.

Current Part Number	New Part Number
ZL1505ALNNT	ZL1505ALNFT
ZL1505ALNNT1	ZL1505ALNFT1
ZL1505ALNNT6	ZL1505ALNFT6
ZL2004ALNN	ZL2004ALNF
ZL2004ALNN-01	ZL2004ALNF-01
ZL2004ALNNT	ZL2004ALNFT
ZL2004ALNNT-01	ZL2004ALNFT-01
ZL2004ALNNT1	ZL2004ALNFT1
ZL2004ALNNT1-01	ZL2004ALNFT1-01
ZL2014ALANT-01	ZL2014ALAF-01
ZL2014ALANT1-01	ZL2014ALAF1-01
ZL2014ALANT6-01	ZL2014ALAF6-01
ZL2014ALANT6-02	ZL2014ALAF6-02
ZL2014ALANT6-04	ZL2014ALAF6-04
ZL2014ALANT6-08	ZL2014ALAF6-08

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

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PCN10118

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PCN10118 - Reliability Qualification Plan

Reliability Test	ZL1505 (2.5UM TOP METAL) fab'ed using BCD35 10 LEAD 3X3 DFN at SCM	ZL2014 (2.5UM TOP METAL) fab'ed using BCD35 32 LEAD 5X5 TQFN at SCM
High Temperature Operating Life	SRN100355 Rev 0 0/160 125C 168hr (Passed 500hrs) est. risk release date of 2010-11-23 risk release: 1000 SRN100355 Rev 1 0/80 (Passed 168hrs) est. risk release date of 2010-12-8 risk release: 1000	SRN100345 Rev 0 0/234 125C 168hr (Passed 500hrs) est. risk release date of 2010-11-24 risk release: 1000
Temperature/Humidity/Bias	NA	NA
Biased HAST	SRN100355 Rev 0 0/81 130C, 85%RH PRECOND L2 PBFREE fcst. complete date of 2010-11-30	SRN100345 Rev 0 0/81 130C, 85%RH PRECOND L2 PBFREE fcst. complete date of 2010-11-4 (Passed 96hrs)
Storage Life	NA	SRN100345 Rev 0 0/78 150C BAKE AND REFLOW due off at 1000hr 2010-11-11 est. risk release date of 2010-11-15 risk release: 1000
Destructive Wire Pull after Storage Life	NA	NA
Bond Pull Integrity	NA	NA
Moisture Sensitivity Classification	MRT10133 MSL=1@260C (Pb Free) Approved=Yes MRT10133 MSL=1@260C (Pb Free) Approved=Yes	MRT10130 MSL=2@260C (Pb Free) Approved=Yes MRT10130 MSL=2@260C (Pb Free) Approved=Yes
Unbiased HAST	SRN100355 Rev 0 0/81 130C, 85%RH PRECOND L2 PBFREE (Passed 96hrs)	SRN100345 Rev 0 0/81 130C, 85%RH PRECOND L2 PBFREE (Passed 96hrs)

PCN10118 - Reliability Qualification Plan – cont.

Reliability Test	ZL1505 (2.5UM TOP METAL) fab'ed using BCD35 10 LEAD 3X3 DFN at SCM	ZL2014 (2.5UM TOP METAL) fab'ed using BCD35 32 LEAD 5X5 TQFN at SCM
Temperature Cycle	SRN100355 Rev 0 0/81 -65C TO 150C PRECOND L2 PBFREE (Passed 200cyc) fcst. complete date of 2010-11-15	SRN100345 Rev 0 0/81 -65C TO 150C PRECOND L2 PBFREE (Passed 200cyc) fcst. complete date of 2010-11-30
Destructive Wire Pull after Temp Cycle	NA	NA
Product Electrical Characterization	Performed by Product Engineering	Performed by Product Engineering
Statistical Bin Yield Analysis	Performed by Product Engineering	Performed by Product Engineering
ESD Characterization	HBM 1750V MM 200V CDM 750V	HBM 2000V MM 200V CDM 750V
Latch-up Characterization	Passed 125C	Passed 85C